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- State-of-the-Art EPIC-IIB™ BiCMOS Design Significantly Reduces Power Dissipation
- ESD Protection Exceeds 2000 V Per MIL-STD-883, Method 3015; Exceeds 200 V Using Machine Model (C = 200 pF, R = 0)
- Latch-Up Performance Exceeds 500 mA Per **JEDEC Standard JESD-17**
- Typical V_{OLP} (Output Ground Bounce) < 1 V • at $V_{CC} = 5 V$, $T_A = 25^{\circ}C$
- High-Drive Outputs (-32-mA I_{OH}, 64-mA I_{OL})
- **Package Options Include Plastic** Small-Outline (DW), Shrink Small-Outline (DB), and Thin Shrink Small-Outline (PW) Packages, Ceramic Chip Carriers (FK), Ceramic Flat (W) Package, and Plastic (N) and Ceramic (JT) DIPs

description

The SN54ABT623A and SN74ABT623 bus transceivers are designed for asynchronous communication between data buses. The control-function implementation allows for maximum flexibility in timing. The SN54ABT623A and SN74ABT623 provide true data at their outputs.

These devices allow data transmission from the A bus to the B bus or from the B bus to the A bus, depending on the logic levels at the output-enable (OEAB and OEBA) inputs.

The output-enable inputs can be used to disable the device so that the buses are effectively isolated. The dual-enable configuration gives the transceivers the capability of storing data by simultaneously enabling OEAB and OEBA. Each output reinforces its input in this configuration. When both OEAB and OEBA are enabled and all other data sources to the two sets of bus lines are at high impedance, both sets of bus lines (16 total) remain at their last states.

To ensure the high-impedance state during power up or power down, $\overline{\mathsf{OEBA}}$ should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver. OEAB should be tied to GND through a pulldown resistor; the minimum value of the resistor is determined by the current-sourcing capability of the driver.

The SN54ABT623A is characterized for operation over the full military temperature range of -55°C to 125°C. The SN74ABT623 is characterized for operation from -40°C to 85°C.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

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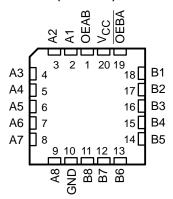
PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.



SN54ABT623A JT OR W PACKAGE
SN74ABT623 DB, DW, N, OR PW PACKAGE

(TOP VI	EW)	
OEAB [A1 [A2 [A3 [A4 [A5 [A6 [A7 [A8 [GND [2 3 4 5 6 7 8	19 18 17 16 15 14	B5 B6

SN54ABT623A . . . FK PACKAGE (TOP VIEW)

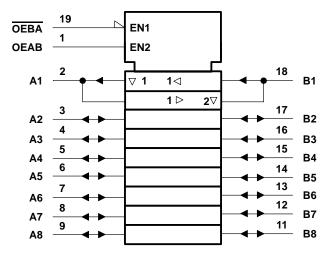


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FUNCTION TABLE

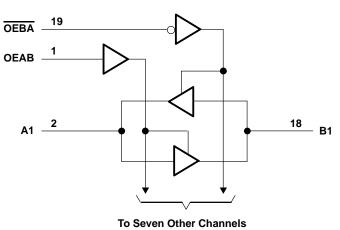
INP	UTS	
OEBA	OEAB	OPERATION
L	L	B data to A bus
L	н	B data to A bus, A data to B bus
н	L	Isolation
н	н	A data to B bus

logic symbol[†]



[†] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram (positive logic)







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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage range, V _{CC} Input voltage range, V _I (except I/O ports) (see Voltage range applied to any output in the high	Note 1) or power-off state, V _O .	
Current into any output in the low state, IO: SN	154AB1623A	
SN	174ABT623	128 mA
Input clamp current, I _{IK} (V _I < 0)		–18 mA
Output clamp current, I_{OK} ($V_O < 0$)		
Package thermal impedance, θ_{JA} (see Note 2)		
	DW package	
	N package	67°C/W
	PW package	128°C/W
Storage temperature range, T _{stg}		

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.

2. The package thermal impedance is calculated in accordance with EIA/JEDEC Std JESD51, except for through-hole packages, which use a trace length of zero.

recommended operating conditions (see Note 3)

		SN54AB	T623A	SN74A			
			MIN	MAX	MIN	MAX	UNIT
Vcc	Supply voltage	4.5	5.5	4.5	5.5	V	
VIH	VIH High-level input voltage				2		V
VIL	VIL Low-level input voltage					0.8	V
VI Input voltage				VCC	0	VCC	V
IOH High-level output current				-24		-32	mA
IOL	IOL Low-level output current					64	mA
$\Delta t/\Delta v$	Input transition rise or fall rate Outputs enabled			5		5	ns/V
Т _А	T _A Operating free-air temperature				-40	85	°C

NOTE 3: Unused pins (input or I/O) must be held high or low to prevent them from floating.



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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS		Т	T _A = 25°C			T623A	SN74ABT623			
				MIN	түр†	MAX	MIN	MAX	MIN	MAX	UNIT	
Vік		V _{CC} = 4.5 V,	lj = -18 mA			-1.2		-1.2		-1.2	V	
		V _{CC} = 4.5 V,	I _{OH} = -3 mA	2.5			2.5		2.5			
Maria		V _{CC} = 5 V,	I _{OH} = -3 mA	3			3		3		V	
VOH		V _{CC} = 4.5 V	I _{OH} = -24 mA	2			2					
		VCC = 4.5 V	I _{OH} = -32 mA	2*					2		1	
Vei		V _{CC} = 4.5 V	I _{OL} = 48 mA			0.55		0.55			V	
VOL		VCC = 4.5 V	I _{OL} = 64 mA			0.55*				0.55	v	
V _{hys}					100						mV	
	Control inputs		VI = VCC or GND			±1		±1		±1	μA	
Ι	A or B ports	V _{CC} = 5.5 V,				±100		±100		±100	μА	
IOZH‡		V _{CC} = 5.5 V,	V _O = 2.7 V			50**		10		50	μΑ	
IOZL [‡]		V _{CC} = 5.5 V,	$V_{O} = 0.5 V$			-50**		-10		-50	μA	
l _{off}		V _{CC} = 0,	VI or VO \leq 4.5 V			±100				±100	μΑ	
ICEX		V _{CC} = 5.5 V, V _O = 5.5 V	Outputs high			50		50		50	μA	
۱ ₀ §		V _{CC} = 5.5 V,	V _O = 2.5 V	-50	-100	-180	-50	-180	-50	-180	mA	
		V _{CC} = 5.5 V,	Outputs high		5	250		250		250	μA	
ICC	A or B ports	$I_{O} = 0,$	Outputs low		22	30		30		30	mA	
		$V_{I} = V_{CC} \text{ or } GND$	Outputs disabled		1	250		250		250	μΑ	
	Data inputs	V _{CC} = 5.5 V, One input at 3.4 V,	Outputs enabled			1.5		1.5		1.5		
$\Delta I_{CC}\P$		Other inputs at V _{CC} or GND	Outputs disabled			0.05		0.05		0.05	mA	
	Control inputs $V_{CC} = 5.5$ V, One in Other inputs at V_{CC}					1.5		1.5		1.5		
Ci	Control inputs	VI = 2.5 V or 0.5 V			4						pF	
C _{io}	A or B ports	V _O = 2.5 V or 0.5 V			7						pF	

* On products compliant to MIL-PRF-38535, this parameter does not apply.

** These limits apply only to the SN74ABT623.

[†] All typical values are at V_{CC} = 5 V.

[‡] The parameters I_{OZH} and I_{OZL} include the input leakage current.

§ Not more than one output should be tested at a time, and the duration of the test should not exceed one second.

This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.



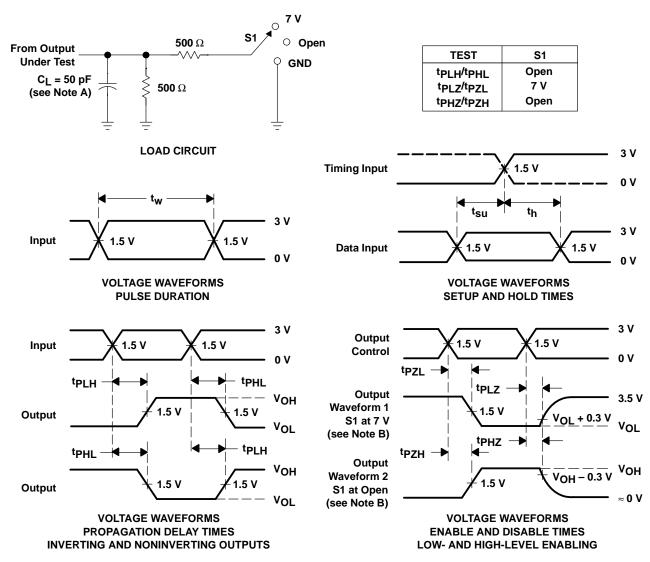
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switching characteristics over recommended ranges of supply voltage and operating free-air temperature, $C_L = 50 \text{ pF}$ (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)			SN54ABT623A		SN74ABT623		UNIT	
		(001101)	MIN	TYP	MAX	MIN	MAX	MIN	MAX	
^t PLH	A or B	B or A	1	2.6	4.1	1	4	1	4.6	ns
^t PHL	AUB	BUIA	1	2.6	4.2	0.8	4.1	1	4.6	115
^t PZH	OEBA	А	1.7	3.4	6.5	1.2	5.4	1.7	7.5	ns
^t PZL		A	1.7	3.8	6.5	1.5	6.8	1.7	7.5	115
^t PHZ	0504	А	1.7	4.2	6.5	1.7	7.1	1.7	7.5	20
^t PLZ	OEBA	A	1.7	4.7	6.5	1.5	7.1	1.7	7.5	ns
^t PZH		В	1.7	4.8	6.5	1.2	6.8	1.7	7.5	
^t PZL	OEAB	В	1.7	4	6.5	1.7	6.5	1.7	7.5	ns
^t PHZ	OEAB	В	1.7	3.9	6.5	1.5	6.8	1.7	7.5	200
^t PLZ		0	1.7	3.2	6.5	1.3	5.8	1.7	7.5	ns



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PARAMETER MEASUREMENT INFORMATION

NOTES: A. CL includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, Z_O = 50 Ω , t_r \leq 2.5 ns, t_f \leq 2.5 ns.
- D. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms



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